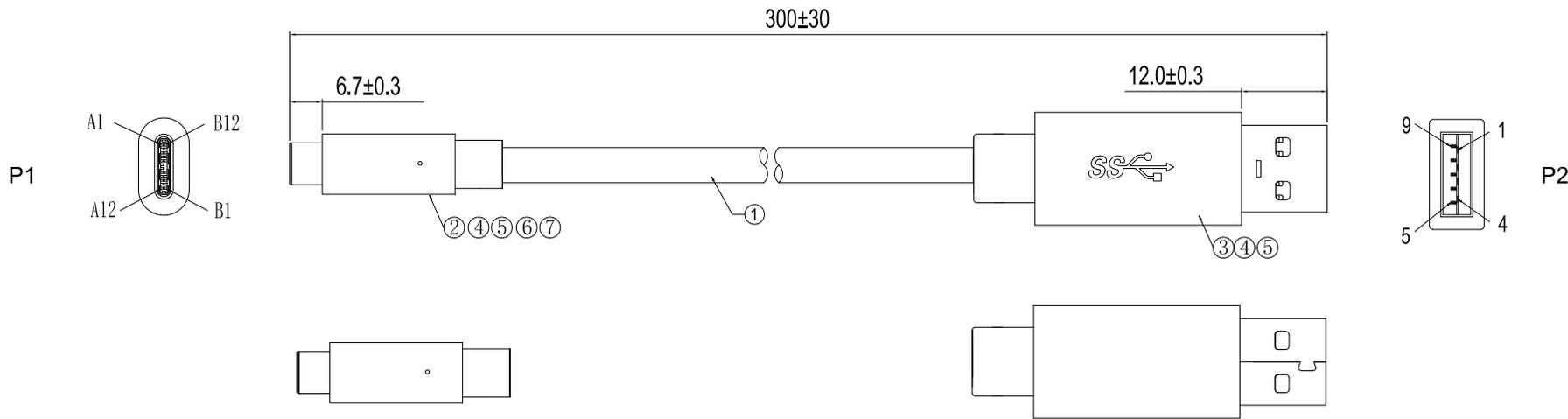


GP Component

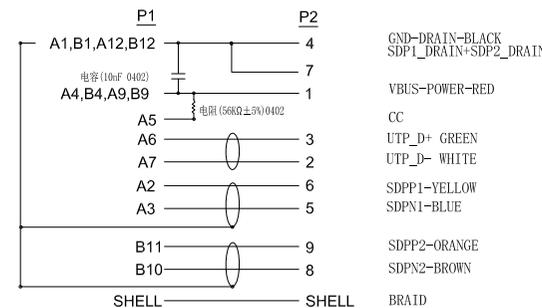
REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2025/05/07	Hanson



ELECTRICAL CHARACTER:

1. OPEN/SHORT/INTERMITTENCE 100% TEST.
2. INSULATION RESISTANCE:5MΩ MIN
3. CONDUCTIVE RESISTANCE:2Ω MAX.
4. Rosh compliant

PIN ASSIGNMENT



NO.	NAME	MATERIAL DESCRIPTION	Q'TY	UNITS
8	TIE	TIE	1	PCS
7	BOTTOM SHELL	SPCC,NI PLATED	1	PCS
6	TOP SHELL	SPCC,NI PLATED	1	PCS
5	OVER MOLD	PVC BLACK	A/R	KG
4	INNER MOLD	PE	A/R	KG
3	CONN	USB3.0 A MALE BLUE INSULATOR SHEEL:NI-PLATED	1	PCS
2	CONN	USB3.1 C TYPE MALE BLACK INSULATOR SHEEL:NI-PLATED	1	PCS
1	CABLE	(7/0.10SC*1P+7/0.10TC+AL+HM)*2C+7/0.080TC*1P+34/0.10TC*2C +AL+B16/8/0.080TC PVC BLACK OD 4.5	A/R	M



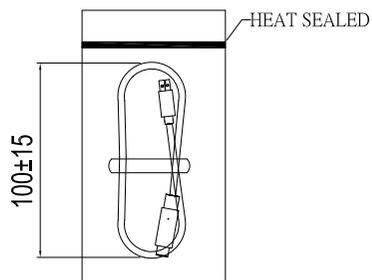
Matrix Electronics Co.,Ltd

<p>TOLERANCE: X.X ±0.35 X.XX ±0.25 X.XXX ±0.20 X.XXX ±0.15 ANGLE: ±5°</p> <p>UNIT: mm [inch] SCALE:1:1 SIZE:A4</p>	DESIGN BY :	DATE :	PART NAME:	
	Hanson	2025/05/07	USB CM TO AM Cable 10G L=300mm	
	CHECKED BY:	DATE :	PART NO.	MCABLE-UTU-093-RS
	Hanson Huang	2025/05/07		
	APPROVED BY1:	DATE :	MOLD NO.	NA
	Richard Hsieh	2025/05/07		
	APPROVED BY2:	DATE :	DRAW NO.	NA
	Richard Hsieh	2025/05/07	SHEET NO.	1 OF 1

GP Component

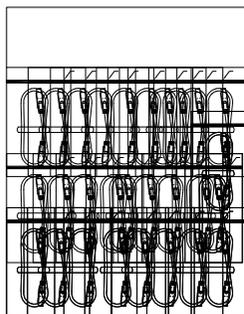
REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2025/05/07	Hanson

Step1 1PCS/PE



PE袋 70*140*0.05mm

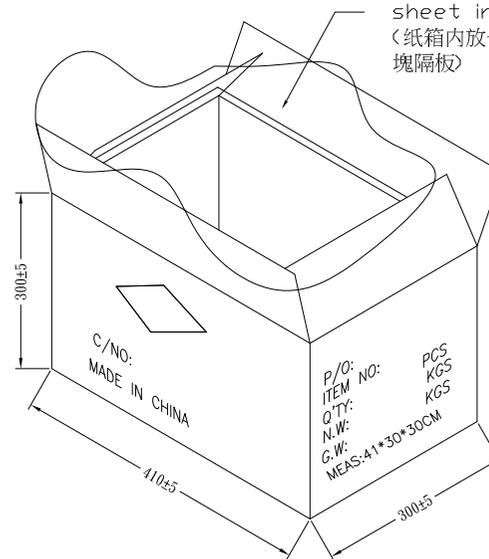
Step2 100PCS/MID PE



MID PE袋 420*300*0.05

Step3

Use waterproof bag to carry products and add top & bottom partition sheet in the carton.
 (纸箱内放一防水袋,成品上下各放一块隔板)

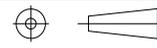


PACKING:

- 1.PCS/PE BAG
- 2.Use waterproof bag to carry products and add top & bottom partition sheet in the carton.
(纸箱内放一防水袋,成品上下各放一块隔板)
- 3.100PCS/MID PE BAG
- 4.600PCS/carton



Matrix Electronics Co.,Ltd

TOLERANCE: X.X ±0.35 X.XX ±0.25 X.XXX ±0.20 X.XXX ±0.15 ANGLE: ±5°	DESIGN BY :	DATE :	PART NAME:	
	Hanson	2025/05/07	PACKING	
 UNIT: mm [inch]	CHECKED BY:	DATE :	PART NO.	MCABLE-UTU-093-RS
	Hanson Huang	2025/05/07	MOLD NO.	NA
SCALE:1:1	APPROVED BY1:	DATE :	DRAW NO.	NA
SIZE:A4	Richard Hsieh	2025/05/07	SHEET NO.	1 OF 1
	APPROVED BY2:	DATE :		
	Richard Hsieh	2025/05/07		